



# BGA/CSP DEVELOPMENT UPDATE SERVICE

## Second Quarter, 2004

The second quarterly BGA/CSP update for 2004 provides analysis of key economic indicators that impact the economy and the semiconductor packaging industry. Included is a discussion on the impact of rising oil prices. The update features special coverage of flip chip substrate developments, including descriptions of substrates offered by companies worldwide. Industry trends for laminate flip chip substrates are discussed, including body size, core thickness, via and pad diameter, minimum bump pitch supported, substrate finish, and substrate price trends. A capacity analysis examines the demand and supply for laminate wire bond, flip chip, and CSP substrates and the impact on prices. The report also includes a special section on IC package assembly price trends.

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